

**POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH
IMPROVED SOLDER FILLER PARTICLE SIZE AND
MICROELECTRONIC PACKAGE APPLICATION**

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ABSTRACT

One embodiment of the invention includes a thermal interface material. The thermal interface material includes a polymer matrix; a plurality of fusible particles dispersed within the polymer matrix; and a plurality of non-fusible particles dispersed within the polymer matrix. The fusible particles have a mean particle size
10 that is greater than the maximum particle size of the non-fusible particles. The thermal interface material improves performance of an integrated circuit.

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